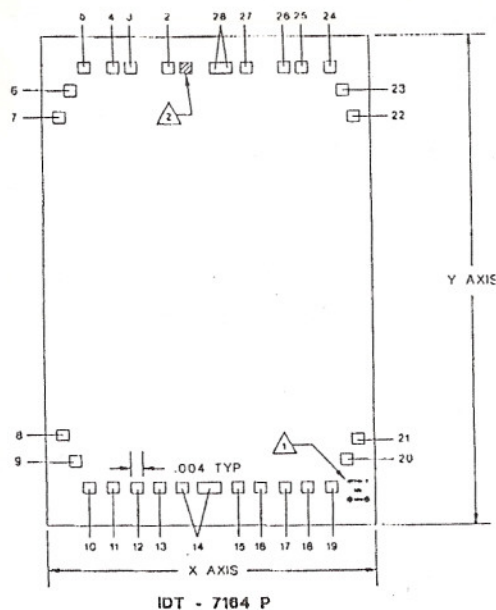




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



- △ Die Mask I.D. Number - IDT7164 P
- △ Metallized Landmark

Dimensions	X Axis	Y Axis	Tolerance	Technical Information
Glass to Glass	.111 inch	.166 inch	Nominal	Pad Metal: Al
Edge to Edge	.113 inch	.171 inch	±.003 inch	Backside Material: Si
Manufacturer	.114 inch	.172 inch	Nominal	Backside Contact: Vcc
Thickness	.021 inch		Nominal	Pad 14 = Gnd
Bond Pads	.004 inch	.004 inch	Nominal	Pad 28 = Vcc
Die Scale	30/1 inch			

Topside Metal: Al
Backside: Si
Backside Potential:
Mask Ref:
Bond Pads : .004"

APPROVED BY: CB
MFG: IDT

DIE SIZE : .113" x .161"
THICKNESS: .020"

DATE: 2/7/01
P/N: IDT7164